# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**  
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>Name / Model</th>
</tr>
</thead>
<tbody>
<tr>
<td>HP EliteBook 8560p Notebook</td>
</tr>
<tr>
<td>Name / Model #3</td>
</tr>
<tr>
<td>Name / Model #4</td>
</tr>
<tr>
<td>Name / Model #5</td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Automatic crossing screw driver</td>
<td>Philip #1</td>
</tr>
<tr>
<td>Automatic crossing screw driver</td>
<td>Trox T8</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the Battery and LARGE_DOOR.
2. Get HDD, ODD and memory.
3. Remove KB, pull out connector.
4. Remove Function PCB and MB from KB_DECK
5. Get Thermal module and CPU.
6. Remove LCD module, tear down LCD Cover.
7. Remove panel and camera
8. 
9. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Exploded diagram
Logic Disassemble Process Sequence

Step 1: Remove BATTERY
Logic Disassemble Process Sequence

Step 2: Remove LARGE_DOOR
Logic Disassemble Process Sequence

Step 3: Take away Memory and EXPRESS_CARD_DOOR
Logic Disassemble Process Sequence

Step 4: Remove HDD
HDD Disassemble Process Sequence

Step 5: Disassemble HDD_MODULE and HDD_BRK
Tool: Philip #1 screwdriver
Step 6: Loosen SCREW:M2.5*L8.0(T8) and Remove ODD

Tool: Trox T8 screwdriver & Philip #1 screwdriver
Step 7: Disassemble ODD_MODULE, ODD_BRK and ODD_BEZEL.
Tool: Philip #1 screwdriver
Logic Disassemble Process Sequence

Step 8: Loosen SCREW:M2.0*L2, Remove MINIPCI_CARD_HALF, MINIPCI_CARD_FULL and MODEM_CARD

Tool: Philip #1 screwdriver
Logic Disassemble Process Sequence

Step 9: Loosen SYSTEM_SCREW four T8 screws.
Tool: Trox T8 screwdriver
Logic Disassemble Process Sequence

Step 10: Loosen SYSTEM SCREW
Tool: Trox T8 screwdriver & Philip #1 screwdriver
Keyboard Disassemble Process Sequence

Step 11: Remove KB from SYSTEM
MB Disassemble Process Sequence

Step 12: Disassemble DISPLAY_MODULE from KB_DECK, SCREW:M2.5*L6.0(*)
Tool: Philip #1 screwdriver
Display Disassemble Process Sequence

Step 13: Disassemble FUNCTION_PCIE from KB_DECK, SCREW:M2.5*L6 (∗)
Tool: Philip #1 screwdriver
Step 14: Remove MB from KB_DECK

SCREW: M2.5*L6 (*)

Tool: Philip #1 screwdriver
MB Disassemble Process Sequence

Step 15: Remove CPU and THERMAL MODULE from MB
Display Disassemble Process Sequence

Step 17: Take away LCD_Bezel, SCREW:M2.5*L6.0(2)
Tool: Philip #1 screwdriver
Step 18: Break down LCD_COVER, SCREW:M2.5*L4.0(2), M2.5*L5.0(4)
Tool: Philip #1 screwdriver
Display Disassemble Process Sequence

Step 19: Disassemble PARK_LCD_HINGE_R and LCD_PANEL, SCREW:M2.0*L3(4)
Step 20: Disassemble PARK_LCD_HINGE_L and LCD_PANEL, SCREW:M2.0*L3(4)
Tool: Philip #1 screwdriver